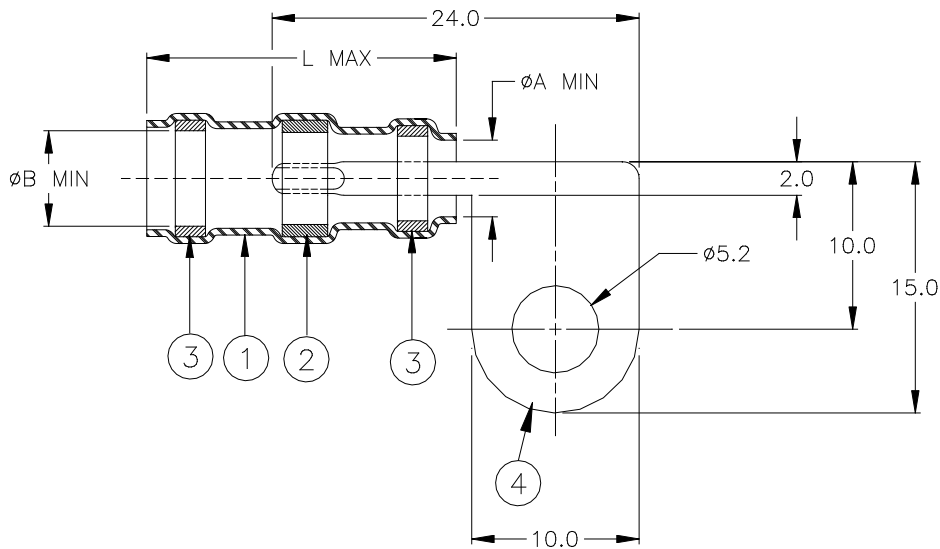


CUSTOMER DRAWING



Product Name	Product Dimensions			Cable Dimensions		
	ϕA min	ϕB min	L max	ϕE min	ϕG max	J ± 0.5 (J ± 0.020)
B-150-05-F	4.3 (0.169)	4.8 (0.189)	18.5 (0.728)	2.0 (0.078)	4.3 (0.169)	6.5 (0.256)
B-150-07-F	6.8 (0.267)	7.3 (0.287)	21.0 (0.827)	3.3 (0.130)	6.8 (0.267)	8.0 (0.315)

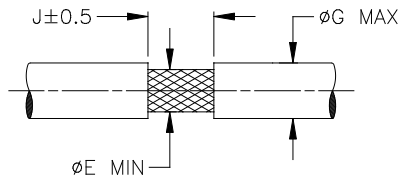
MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent clear, radiation cross-linked modified polyolefin.
2. SOLDER PREFORM WITH FLUX.
SOLDER: TYPE Cd18 per ANSI-J-STD-006.
FLUX: TYPE ROM1 per ANSI-J-STD-004.
3. MELTABLE SEALING RINGS: Thermally stabilized thermoplastic.
4. GROUNDING BAR: Tin plated brass alloy.


APPLICATION

1. These controlled soldering, grounding devices are designed for termination of a bare or tin plated copper shield on a cable having an insulation rated for at least +85°C.
2. Temperature range: -55°C to +125°C.
3. For installation procedure and application equipment, consult RPIP-688-02.

For best results, prepare the cable as shown:



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		Raychem THERMOFIT DEVICES		TITLE: SOLDERSLEEVE WITH FLAG TERMINAL	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO: B-150-XX-F	
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		Revision: 2	Issue Date: April 2020
PREPARED BY: M. FORONDA	DATE: 10/20/99	ECO: ECO-20-004959	SCALE: None	SIZE: A	SHEET: 1 of 1

Print Date: 21-Apr-20 If this document is printed it becomes uncontrolled. Check for the latest revision.